



## **Advances in 3D Printed Electronics: Materials, Processes, Properties and Applications**

Haibin Tang<sup>1,\*</sup> and Xingzhi Xiao<sup>2</sup>

- <sup>1</sup> School of Intelligent Manufacturing, Nanjing University of Science and Technology, Nanjing 210094, China
- <sup>2</sup> School of Mechanical Engineering, Nanjing University of Science and Technology, Nanjing 210094, China; xingzhi.xiao@njust.edu.cn
- \* Correspondence: htang28@njust.edu.cn

The current Special Issue entitled "Advances in 3D printed electronics: materials, processes, properties and applications" aims to discuss the latest developments in the field of the AM of structures or components with reinforcements [1] or conductive elements [2].

Additive manufacturing (AM) shows prominent advantages in the modern industry owing to the almost unlimited design freedom it provides to produce components with complex 3D shapes without the need for tooling [3,4]. In order to fabricate structures or components for real-world applications with high performances or multiple functions, reinforcements or conductive elements are introduced in the latest AM techniques. The methodology and mechanism of multi-functional AM are meaningful to its further development.

The topics addressed in this Special Issue include new computational models and approaches to predicting the fabrication processes and mechanical properties of complex structures and components and new additive manufacturing technologies that cover various types of material extrusion, material lamination, binder jetting, ink writing [5], selective laser sintering [6], curing and sintering, etc. New composite systems containing either fiber reinforcements or conductive elements are covered. The applications of the AM of integrated structures in other fields, e.g., the design of robots and bio-inspired structures, are also welcome.

Funding: This work was supported by the National Natural Science Foundation of China.

Conflicts of Interest: The authors declare no conflict of interest.

## References

- 1. Tang, H.; Sun, Q.; Li, Z.; Su, X.; Yan, W. Longitudinal compression failure of 3D printed continuous carbon fiber reinforced composites: An experimental and computational study. *Compos. Part A Appl. Sci. Manuf.* **2021**, *146*, 106416. [CrossRef]
- MacDonald, E.; Wicker, R. Multiprocess 3D printing for increasing component functionality. Science 2016, 353, aaf2093. [CrossRef] [PubMed]
- 3. Tang, H.; Huang, H.; Liu, C.; Liu, Z.; Yan, W. Multi-scale modelling of structure-property relationship in additively manufactured metallic materials. *Int. J. Mech. Sci.* **2021**, *194*, 106185. [CrossRef]
- Tang, D.; Yang, K.; Gao, T.; Liu, T.; Tang, H. Mechanical-electromagnetic integration design of Al<sub>2</sub>O<sub>3</sub>/SiO<sub>2</sub> ceramic cellular materials fabricated by digital light processing. *Thin-Walled Struct.* 2023, 183, 110437. [CrossRef]
- 5. Tang, D.; Tang, H. Self-healing diamond/geopolymer composites fabricated by extrusion-based additive manufacturing. *Addit. Manuf.* **2022**, *56*, 102898. [CrossRef]
- 6. Tang, H.; Chen, H.; Sun, Q.; Chen, Z.; Yan, W. Experimental and computational analysis of structure-property relationship in carbon fiber reinforced polymer composites fabricated by selective laser sintering. *Compos. Part B Eng.* **2021**, 204, 108499. [CrossRef]



Citation: Tang, H.; Xiao, X. Advances in 3D Printed Electronics: Materials, Processes, Properties and Applications. *Materials* **2023**, *16*, 5975. https:// doi.org/10.3390/ma16175975

Received: 28 August 2023 Accepted: 28 August 2023 Published: 31 August 2023



**Copyright:** © 2023 by the authors. Licensee MDPI, Basel, Switzerland. This article is an open access article distributed under the terms and conditions of the Creative Commons Attribution (CC BY) license (https:// creativecommons.org/licenses/by/ 4.0/).

## Short Biography of Authors

**Haibin Tang** graduated with a degree in Flight Vehicle Propulsion Engineering from the Nanjing University of Aeronautics and Astronautics in 2012, and he received his PhD in Mechanical Engineering from the Nanjing University of Aeronautics and Astronautics in 2019. From 2019 to 2021, he worked at the National University of Singapore as a research fellow. In 2021, he joined the Nanjing University of Science and Technology as an associate professor.

Xingzhi Xiao graduated from the Nanjing University of Science and Technology in 2012, and he received his PhD from the School of Mechanical Engineering at the Nanjing University of Science and Technology in 2018. He is currently an associate professor at the Nanjing University of Science and Technology.

**Disclaimer/Publisher's Note:** The statements, opinions and data contained in all publications are solely those of the individual author(s) and contributor(s) and not of MDPI and/or the editor(s). MDPI and/or the editor(s) disclaim responsibility for any injury to people or property resulting from any ideas, methods, instructions or products referred to in the content.